

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1 BRS	719	(adhesive near resin) with (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 10:55		
2 BRS	51	((adhesive near resin) with (chip or die)) and tape and (ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 10:56		
3 BRS	115	((adhesive near resin) with (chip or die)) and tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 10:56		
4 BRS	83	((adhesive near resin) with (chip or die)) and tape) and (water or vapor or moisture or porous or gap or stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:26		
5 BRS	1	"5703405".PN.	USPAT	2001/11/13 11:13		
6 BRS	1	"5604379".PN.	USPAT	2001/11/13 11:13		
7 BRS	1	"5352926".PN.	USPAT	2001/11/13 11:14		
8 BRS	23349	((water or vapor or moisture or porous or gap or stress)with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:53		
9 BRS	21140	((water or vapor or moisture or porous or gap)with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:42		
10 BRS	119	((water or vapor or moisture or porous or gap or stress)with tape)) and (adhesive adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:30		
11 BRS	113	((((water or vapor or moisture or porous or gap or stress)with tape)) and (adhesive adj resin)) not (((adhesive near resin) with (chip or die)) and tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:31		
12 BRS	35	((((water or vapor or moisture or porous or gap or stress)with tape)) and (adhesive adj resin)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:43		
13 BRS	1618	((water or vapor or moisture or porous or gap or stress)near tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:43		
14 BRS	35	(((((water or vapor or moisture or porous or gap or stress)with tape)) and (adhesive adj resin)) and (chip or die)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:53		
15 BRS	0	(((((water or vapor or moisture or porous or gap or stress)with tape)) and (adhesive adj resin)) and (chip or die)) and (adhesive adj resin)) and (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:44		
16 BRS	2622	(POR\$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:46		Truncation Overflow. Return string from Server is: 5'0'0'POR
17 BRS	420	((POR\$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 15:49		
18 BRS	98	((((POR\$ OR GAP OR STRESS OR SPACE OR HOLE) NEAR TAPE) and (chip or die)) AND ADHESIVE AND RESIN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		
19 BRS	3579	((ball or bump) with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:51		
20 BRS	381	((ball or bump) near tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		
21 BRS	81	((ball or bump) near tape)) AND ADHESIVE AND RESIN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 11:52		
22 BRS	73	((ball or bump) near tape)) AND ADHESIVE AND RESIN) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/13 12:29		
23 IS&R	1	("5258330").PN.	USPAT	2001/11/13 12:29		

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1 BRS	L3	13	(POR\$ NEAR TAPE) and (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 15:51		Truncation Overflow. Return string from Server is: 5'0'0'POR	1
2 BRS	L4	10891	((water or vapor or moisture)with tape)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 15:54			0
3 BRS	L5	1217	L4 and (chip or die)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:07			0
4 BRS	L6	597	L5 and (hole\$ or porous or pore or gap)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:09		Truncation Overflow. Return string from Server is: 5'0'0'HOL	1
5 BRS	L7	248	L5 and ((hole\$ or porous or pore or gap) with (tape or polyimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:30		Truncation Overflow. Return string from Server is: 5'0'0'HOL	1
6 BRS	L8	538	257/668.ccls. and (tape or polyimide)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:31			0
7 BRS	L9	132	L8 and (water or moisture or vapor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:32			0
8 BRS	L10	146	L8 and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:44			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9 BRS	L11	44	257/736.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:45 DERWENT ; IBM TDB	2001/11/13 16:45			0
10 BRS	L12	300	257/737.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:45 DERWENT ; IBM TDB	2001/11/13 16:45			0
11 BRS	L13	235	257/738.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:45 DERWENT ; IBM TDB	2001/11/13 16:45			0
12 BRS	L14	123	257/719.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:45 DERWENT ; IBM TDB	2001/11/13 16:45			0
13 BRS	L15	312	257/778.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:46 DERWENT ; IBM TDB	2001/11/13 16:46			0
14 BRS	L16	201	257/783.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:46 DERWENT ; IBM TDB	2001/11/13 16:46			0
15 BRS	L17	171	257/678.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:46 DERWENT ; IBM TDB	2001/11/13 16:46			0
16 BRS	L18	184	257/668.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; 2001/11/13 JPO; 16:46 DERWENT ; IBM TDB	2001/11/13 16:46			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1 BRS	L3	13	(PORS NEAR TAPE) and (chip or die)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 15:51		Truncation Overflow. Return string from Server is: 5'0'0'POR	1
2 BRS	L4	10891	((water or vapor or moisture)with tape)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 15:54			0
3 BRS	L5	1217	L4 and (chip or die)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:07			0
4 BRS	L6	597	L5 and (hole\$ or porous or pore or gap)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:09		Truncation Overflow. Return string from Server is: 5'0'0'HOL	1
5 BRS	L7	248	L5 and ((hole\$ or porous or pore or gap) with (tape or polyimide))	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:30		Truncation Overflow. Return string from Server is: 5'0'0'HOL	1
6 BRS	L8	538	257/668.ccls. and (tape or polyimide)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:31			0
7 BRS	L9	132	L8 and (water or moisture or vapor)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:32			0
8 BRS	L10	146	L8 and (water or moisture or vapor or crack)	USPAT; US-PGPGU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:44			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9 BRS	L11	44	257/736.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:45			0
10 BRS	L12	300	257/737.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:45			0
11 BRS	L13	235	257/738.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:45			0
12 BRS	L14	123	257/719.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:45			0
13 BRS	L15	312	257/778.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:46			0
14 BRS	L16	201	257/783.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:46			0
15 BRS	L17	171	257/678.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:46			0
16 BRS	L18	184	257/668.ccls. and (water or moisture or vapor or crack)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/11/13 16:46			0
17 BRS	L19	1825	tape and (water adj (permeab\$ or absorb\$))	USPAT	2001/11/13 16:49			0
18 BRS	L20	431	L19 and (semiconductor or chip or die)	USPAT	2001/11/13 16:49			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
19	BRS	L21	18	L19 and (g/m)	USPAT	2001/11/13 16:54			0
20	BRS	L22	25	((tape or resin) and ((water or moisture or vapor) with (g/m))	USPAT	2001/11/13 17:10			0
21	BRS	L23	28	((tape or resin) with (g/m)) and (water or moisture or vapor)	USPAT	2001/11/13 17:12			0
22	BRS	L24	2	(tape with (g/m)) and (semiconductor or chip or die)	USPAT	2001/11/13 17:09			0
23	BRS	L25	5	tape and ((water or moisture or vapor) with (g/m))	USPAT	2001/11/13 17:10			0
24	BRS	L26	7	L23 and ((semiconductor adj device) or chip or die)	USPAT	2001/11/13 17:12			0